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| .0                              | 5)<br>F     | ORM P   | TO-1449           |  | ATTY. DOCKET NO.<br>1875.0370000                            |                                  | APPLICATION NO<br>09/849,537           | Page 1 of 4                 |
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| MC                              | AA1         | 5,65  | 0,662             | 07/1997  | Edwards et al.  |                                  |  |                             |
|                                 | AB1         | 5,88  | 9,321             | 03/1999  | Culnane et al.  |                                  |  |                             |
|                                 | AC1         | 5,89  | 5,967             | 04/1999  | Steams et al.   |                                  |  |                             |
|                                 | AD1         | 5,90  | 7,189             | 05/1999  | Mertol  |                                  |  | <u> </u>                    |
|                                 | AE1         | 5,97  | 6,912             | 11/1999  | Fukutomi et al.   |                                  |  |                             |
|                                 | AF1         | 5,97  | 7,633             | 11/1999  | Suzuki et al.   |                                  |  |                             |
|                                 | AG1         | 6,03  | 4,427             | 03/2000  | Lan et al.  |                                  |  |                             |
|                                 | AH1         | 6,04  | 0,984             | 03/2000  | Hirakawa  |                                  |  |                             |
|                                 | Al1         | 6,20  | 7,467 B1          | 03/2001  | Vaiyapuri et al.  |                                  |  |                             |
| 7                               | AJ1         | 6,27  | 8,613 B1          | 08/2001  | Fernandez et al.  |                                  |  |                             |
| W                               | AK1         | 6,31  | 3,525 B1          | 11/2001  | Sasano  |                                  |  |                             |
| EXAMINER                        |             | Inoc  | UMENT             | FOREIGN  | PATENT DOCUMEN  | ITS                              |  | ·                           |
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|                                 | AL1         |   |                   |  |   |                                  |  | No.                         |
|                                 | AM1         |   |                   |  |   |                                  |  | Yes<br>No                   |
| J                               | AN1         |   |                   |  |   |                                  |  | Yes<br>No                   |
|                                 | AO1         |   |                   |  |   |                                  |  | Yes<br>No                   |
|                                 | AP1         |   |                   |  |   |                                  |  | Yes                         |
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| MU                              | AR          | 1   | Amkor pack        | kage data she<br>amkor.com/P   | et, "SuperFC <sup>®</sup> ", from<br>roducts/all_datasheets | s/superfc.pdf, 2                 | 2 pages (Jan. 20                       | 03).                        |
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| M                               | AT          | 1   | Area Array        | .J. <i>et al.</i> , "Flip<br><i>Interconnectio</i><br>Publishers (20 | -Chip Die Attach Tech<br>on Handbook, pp. 315-<br>01).      | nology," Puttli<br>-349, ISBN No | tz, K.J. and Totta<br>b. 0-7923-7919-5 | a, P.A. (eds.),<br>, Kluwer |
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| MC                  | AA2          | 6,52   | 8,869 B1          | 03/2003   | Glenn et al.   |                |                               |                  |  |  |  |
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|                     | AC2          | 6,61   | 7,193 B1          | 09/2003   | Toshio et al.  |                |                               |                  |  |  |  |
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|                     | Al2          | 2001   | /0040279 A1       | 11/2001   | Mess et al.  |                |                               | (                |  |  |  |
| V                   | AJ2          | 2002   | 2/0171144 A1      | 11/2002   | Zhang et al.   |                |                               |                  |  |  |  |
| MC                  | AK2          | 2002   | V0185717 A1       | 12/2002   | Eghan et al.   |                |                               |                  |  |  |  |
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|                     | AL2          |        |                   |   |  |                |                               | Yes              |  |  |  |
|                     | AM2          |        |                   |   |  |                |                               | Yes              |  |  |  |
|                     | AN2          |        |                   |   |  |                |                               | Yes<br>No        |  |  |  |
|                     | AO2          |        |                   |   |  |                |                               | Yes              |  |  |  |
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| W                   | AR           | 2      |                   |   | i, M., "High-Pincount PB0<br>lay/June 1995).             | GAs," Advar    | nced Packaging,               | pp. 44-46, An    |  |  |  |
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| AH3  AI3  AI3  AK3  FOREIGN PATENT DOCUMENTS  EXAMINER INITIAL  AL3  AM3  AN3  AN3  AN3  AN3  AP3  OTHER (Including Author, Title, Date, Pertinent Pages, etc.)  AR 3  Lin, S. and Chang, N., "Challenges in Power-Ground Integrity," Proceedings Of The 2001 International Conference On Computer-Alded Design, pp. 651-654 (November 4-8, 2001).  AS 3  Lloyd, J. and Overhauser, D., "Electromigration wreaks havoc on IC design," EDN, pp. 144 148 (March 26, 1998).  AT 3  Song, W.S. and Glasser, L.A., "Power Distribution Techniques for VLSI Circuits," IEEE Journal of Solid-State Circuits, Vol. SC-21, No. 1, pp. 150-156 (February 1986).  EXAMINER: Initial If reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance   |                  | AF3            |  |  |   |                 |                                    |                              |  |  |
| AX3  AX3  AX3  AX3  AX3  AX3  AX3  AX3   |                  | AG3            |  |  |   |                 |                                    |                              |  |  |
| AX3  AK3  FOREIGN PATENT DOCUMENTS  EXAMINER   DOCUMENT   NUMBER   DATE   COUNTRY   CLASS   SUB-CLASS   TRANSLATION    AL3   AM3   AN3   AN3   AN3   AN3   AN3   AN3   AN3   AN4   AN4   AN5   A |                  | АНЗ            |  |  |   |                 |                                    | ·                            |  |  |
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| AN3  AO3  AP3  OTHER (Including Author, Title, Date, Pertinent Pages, etc.)  Lin, S. and Chang, N., "Challenges in Power-Ground Integrity," Proceedings Of The 2001 International Conference On Computer-Aided Design, pp. 651-654 (November 4-8, 2001).  AS 3 Lloyd, J. and Overhauser, D., "Electromigration wreaks havoc on IC design," EDN, pp. 145, 148 (March 26, 1998).  AT 3 Song, W.S. and Glasser, L.A., "Power Distribution Techniques for VLSI Circuits," IEEE Journal Of Solid-State Circuits, Vol. SC-21, No. 1, pp. 150-156 (February 1986).  EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance  |                  |                |  | <del> </del>   |   |                 |                                    | No.                          |  |  |
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| nd not consider<br>24516_1.DOC |              | е сору   | or this torm wi         | ui next communi   | cation to Applicant.                    |                    |                               |  |  |  |